ON Semiconductor

Is Now

Onsemi

To learn more about onsemi[™], please visit our website at <u>www.onsemi.com</u>

onsemi and ONSEMI: and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application is provided for uses as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi roducts for any such unintended or unauthorized application, Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs

<u>MOSFET</u> – Power, N-Channel, SUPERFET[®] III 800 V, 450 mΩ, 11 A

NTPF450N80S3Z

Description

800 V SUPERFET III MOSFET is ON Semiconductor's high performance MOSFET family offering 800 V breakdown voltage.

New 800 V SUPERFET III MOSFET which is optimized for primary switch of flyback converter, enables lower switching losses and case temperature without sacrificing EMI performance thanks to its optimized design. In addition, internal Zener Diode significantly improves ESD capability.

This new family of 800 V SUPERFET III MOSFET enables to make more efficient, compact, cooler and more robust applications because of its remarkable performance in switching power applications such as Laptop adapter, Audio, Lighting, ATX power and industrial power supplies.

Features

- Typ. $R_{DS(on)} = 380 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Qg = 19.3 nC)
- Low Stored Energy in Output Capacitance (Eoss = 2.2 µJ @ 400 V)
- 100% Avalanche Tested
- ESD Improved Capability with Zener Diode
- RoHS Compliant

Applications

- Adapters / Chargers
- LED Lighting
- AUX Power
- Audio
- Industrial Power

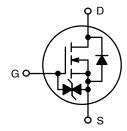


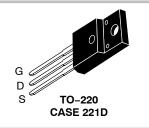
ON Semiconductor®

www.onsemi.com

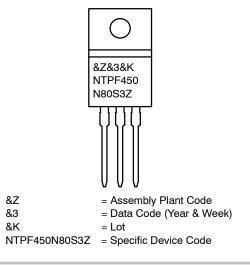
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
800 V	450 m Ω @ V _{GS} = 10 V	11 A	







MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Para	Value	Unit	
V _{DSS}	Drain-to-Source Voltage	800	V	
V _{GS}	Gate-to-Source Voltage	DC	±20	V
		AC (f > 1 Hz)	±30	V
I _D	Drain Current	Continuous (T _C = 25°C)	11*	А
		Continuous (T _C = 100°C)	7*	А
I _{DM}	Drain Current Pulsed (Note 1)		25*	А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		32	mJ
I _{AS}	Avalanche Current (Note 2)		1.55	А
E _{AR}	Repetitive Avalanche Energy (Note 1)		0.295	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		10	V/ns
PD	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	29.5	W
		Derate above 25°C	0.236	W/°C
T _J , T _{stg}	Operating Junction and Storage Temperature Range		-55 to +150	°C
ΤL	Lead Temperature for Soldering Purposes (1/8" from Case for 10 seconds)		260	°C

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
*Drain current limited by maximum junction temperature
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I_{AS} = 1.55 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 2.75 A, di/dt ≤ 200 A/µs, V_{DD} ≤ 400 V, starting T_J = 25°C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction-to-Case, Max.	4.23	°C/W
R _{θJA}	R _{0JA} Thermal Resistance, Junction-to-Ambient, Max.		

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTPF450N80S3Z	NTPF450N80S3Z	TO-220F	Tube	N/A	N/A	50 Units

FLECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•		•	
BV _{DSS}	Drain-to-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	800 –		-	V
		$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 150^{\circ}\text{C}$	900	_	-	V
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Drain-to-Source Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Reference to 25°C	-	1.1	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 640 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	0.8	-	
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20$ V, $V_{DS} = 0$ V	-	-	±1	μA
ON CHARACTE	RISTICS		•		•	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.24 \text{ mA}$	2.2	-	3.8	V
R _{DS(on)}	Static Drain-to-Source On Resistance	V_{GS} = 10 V, I _D = 5.5 A	-	380	450	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 5.5 A	-	11.8	-	S
OYNAMIC CHA	RACTERISTICS				I.	
C _{iss}	Input Capacitance	$V_{\rm D} = 400 \text{ V}, V_{\rm GS} = 0 \text{ V},$	-	885	-	pF
C _{oss}	Output Capacitance	f = 250 kHz	-	15	-	-
C _{oss(eff.)}	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	188	-	1
C _{oss(er.)}	Energy Related Output Capacitance		-	27	-	-
Q _{g(tot)}	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	19.3	-	nC
Q _{gs}	Gate-to-Source Charge	(Note 4)	-	4.2	-	-
Q _{gd}	Gate-to-Drain "Miller" Charge		-	6.6	-	
ESR	Equivalent Series Resistance	f = 1 MHz	-	4.0	-	Ω
	IARACTERISTICS				I.	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 5.5 A,	-	13.3	-	ns
t _r	Turn–On Rise Time	V _{GS} = 10 V, R _G = 4.7 Ω (Note 4)	-	6.7	-	
t _{d(off)}	Turn-Off Delay Time		-	44.3	-	
t _f	Turn-Off Fall Time		-	4.6	-	
OURCE-TO-E	DRAIN DIODE CHARACTERISTICS				I	
۱ _S	Maximum Continuous Source-to-Drain	Diode Forward Current	-	-	11	Α
I _{SM}	Maximum Pulsed Source-to-Drain Dio	de Forward Current	_	_	25	Α
V _{SD}	Source-to-Drain Diode Forward Volt- age	V _{GS} = 0 V, I _{SD} = 5.5 A	-	-	1.2	V
			-			I

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

 V_{GS} = 0 V, I_{SD} = 2.75 A, $di_{F}/$ dt = 100 A/ μs

170

1.5

_

_

_

_

ns

μC

Reverse Recovery Time

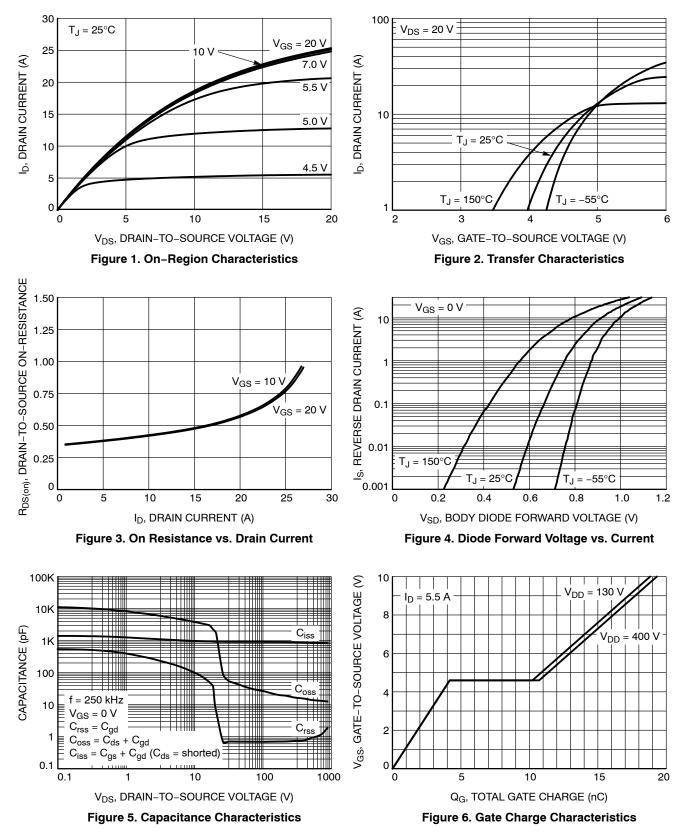
Reverse Recovery Charge

t_{rr}

Q_{rr}

SUPERFET is a registered trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

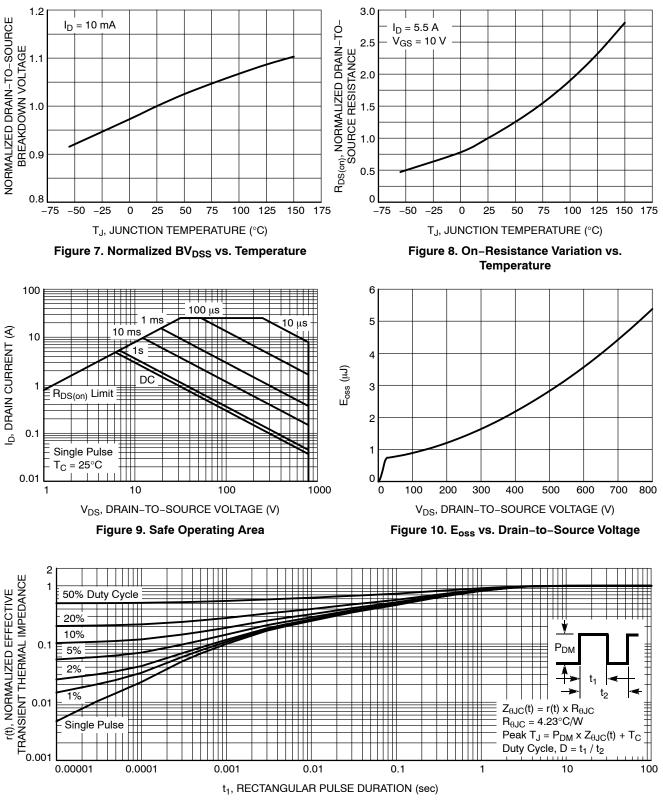


Figure 11. Transient Thermal Impedance

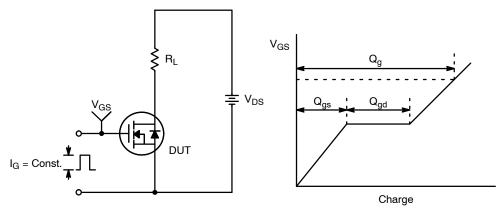


Figure 12. Gate Charge Test Circuit & Waveform

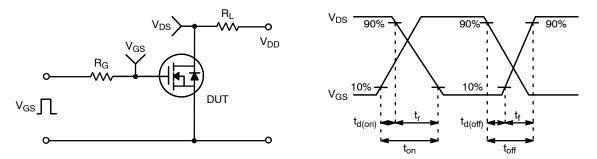


Figure 13. Resistive Switching Test Circuit & Waveforms

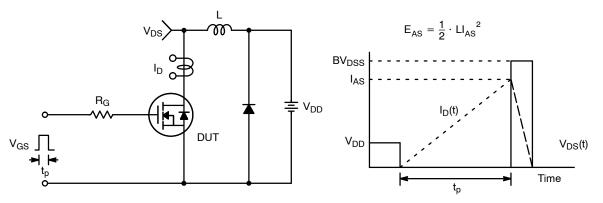
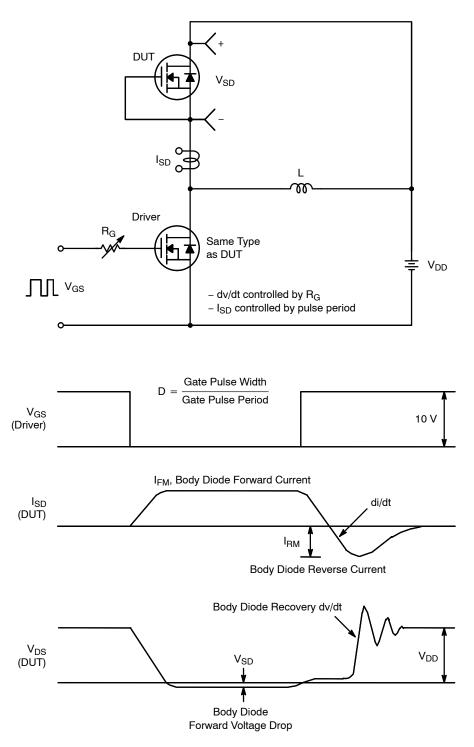
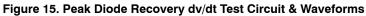


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

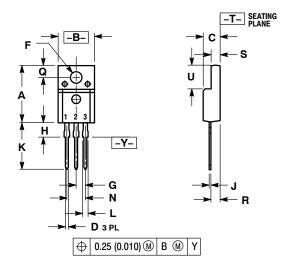




PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03

ISSUE K



NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH 3. 221D-01 THRU 221D-02 OBSOLETE, NEW

221D-01 THRU 221D-02 OE STANDARD 221D-03.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
С	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100	0.100 BSC		BSC
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
Ν	0.200	BSC	5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor date sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use a a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor houteds for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910 Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative

٥